Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field*	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2025-06-30
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U5A9VJT6Q	251L*481XXXW	A	9991	2025-06-30
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	666	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	14x14	100	Gull wing	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**
,	

QueryList : REACH-21st January 2025				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**251L*481XXXW**		665.7517		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	28.660	mg	supplier	die	Silicon (Si)	7440-21-3		27.562	mg	961672	19395.95
				supplier	metallization	Aluminium (Al)	7429-90-5		0.121	mg	4229	85.29
				supplier	metallization	Copper (Cu)	7440-50-8		0.362	mg	12619	254.51
				supplier	passivation	Nickel (Ni)	7440-02-0		0.002	mg	67	1.35
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.062	mg	2148	43.32
				supplier	metallization	Titanium (Ti)	7440-32-6		0.015	mg	537	10.83
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	67	1.35
				supplier	Passivation	Silicon Nitride	12033-89-5		0.087	mg	3021	60.93
				supplier	Passivation	Silicon Oxide	7631-86-9		0.448	mg	15640	315.44
Leadframe (C7025 + Ag)	Copper & its alloys	190.000	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		174.610	mg	919000	262486.71
				supplier	Leadframe	Nickel (Ni)	7440-02-0		5.890	mg	31000	8854.29
				supplier	Leadframe	Silicon (Si)	7440-21-3		2.280	mg	12000	3427.47
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.570	mg	3000	856.87
				supplier	Leadframe	Siliver (Ag)	7440-22-4		6.650	mg	35000	9996.77
Glue Epoxy (EN-4900G)	Precious metals	6.647	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		5.178	mg	779000	4400.72
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.166	mg	25000	141.23
				supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.405	mg	61000	344.60
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.366	mg	55000	310.71
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.066	mg	10000	56.49
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.366	mg	55000	310.71
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.033	mg	5000	28.25
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.033	mg	5000	28.25
				supplier	Glue or tape	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.033	mg	5000	28.25
Bonding wire (Cu)	Precious metals	0.639	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.617	mg	965500	870.85
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.020	mg	31000	27.96
				supplier	Bonding wire	Silver (Ag)	7440-22-4		0.002	mg	3500	3.16
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	418.905	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diy	85954-11-6		16.756	mg	40000	26249.57
				supplier	Molding Compound	Epoxy resin	Proprietary		8.378	mg	20000	13124.79
				supplier	Molding Compound	Phenol Resin	Proprietary		31.418	mg	75000	49217.95
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		297.213	mg	709500	465601.80
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		62.836	mg	150000	98435.90
				supplier	Molding Compound	Carbon black	1333-86-4		2.304	mg	5500	3609.32
External Plating (Sn)	M-011 Other inorganic materials	20.900	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	31415.29
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	3.14